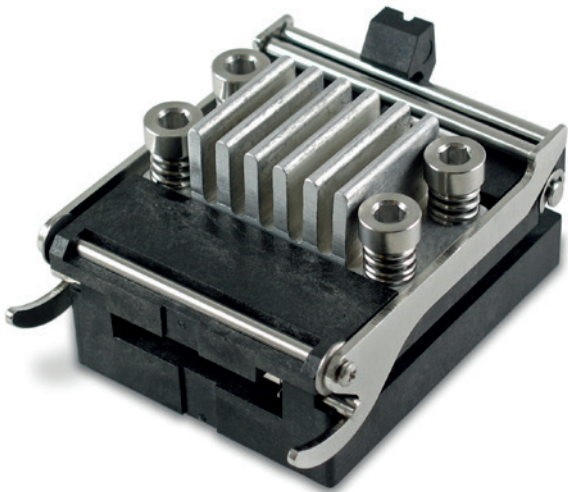


# ES Micro Series H-Pin Socket

Accelerated life testing solution



**ES Micro Series Socket is a technological advancement in the burn-in socket segment, with a dual latch clamshell lid to provide co-planar pressure on the DUT when the lid is actuated.**

The inclusion of the patented H-Pin contact technology in the ES Micro Series socket provides market-leading electrical performance in the smallest footprint for the highest possible parallelism on a burn-in board. This series is compatible with standard heaters and temperature sensors.

Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

## Benefits

- Configurable design, In-house tooling and moulds allow for the lowest cost of test.
- An extensive catalogue of standard parts reduces cost and lead time.
- Double-latching clamshell provides ease of use during operation and clearance for lid operation.
- Exceptional electrical performance provides wide RF bandwidth.

## Feature Options

- LGA, BGA, and package on package
- Spring loaded plunger
- Heat sink
- HAST venting features
- Integrated thermal control with heater and sensor
- Reverse seating plane
- Max component clearance under the DUT
- High temperature materials for above 200 °C applications

## ES Micro Series socket specifications

### Mechanical properties

- Pitch:  $\geq 0.30$  mm
- Package size for BGA: 4 mm to 22 mm
- Pin count: 1190
- Temperature:  $-55^{\circ}\text{C}$  to  $260^{\circ}\text{C}$

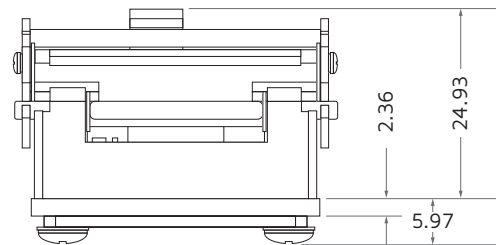
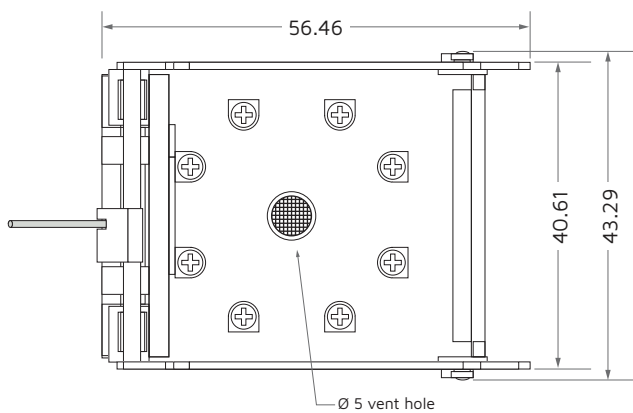
### Electrical properties

- Contact resistance: 35 m $\Omega$
- Current carrying capacity: up to 2.5 A

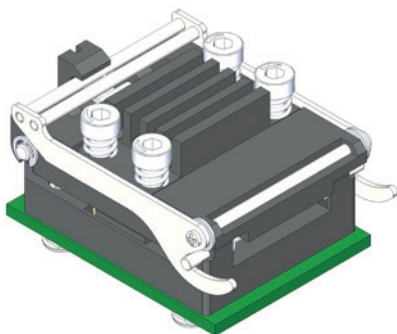
### Materials

- Contact: BeCu/Au plated
- Spring: SS/Au plated
- Socket: Engineering plastics

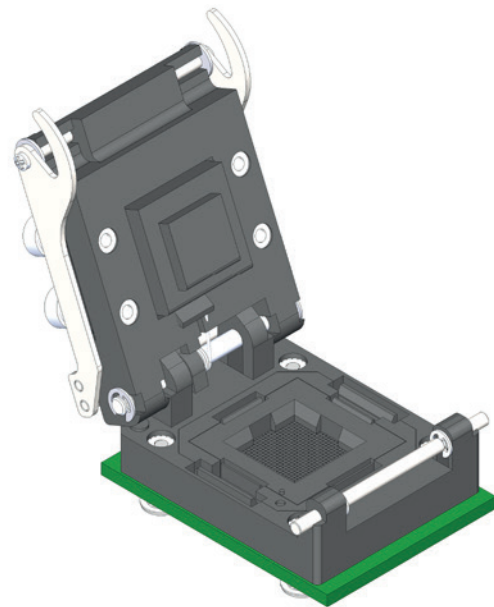
## ES Micro Series socket dimensions



Dimensions are in mm.



Heat sink, heater, and RTD



Spring-loaded plunger

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